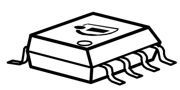
Smart Power High-Side-Switch for Industrial Applications

Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown with restart
- ESD - Protection
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection with external resistor
- CMOS compatible input
- Loss of GND and loss of V_{bb} protection
- Very low standby current

Product Summary

Overvoltage protection	$V_{bb(AZ)}$	62	V
Operating voltage	$V_{bb(on)}$	6 ... 52	V
On-state resistance	R_{ON}	200	mΩ
Nominal load current	$I_{L(nom)}$	1.3	A
Operating temperature	T_a	-30...+85	°C



PG-DSO-8

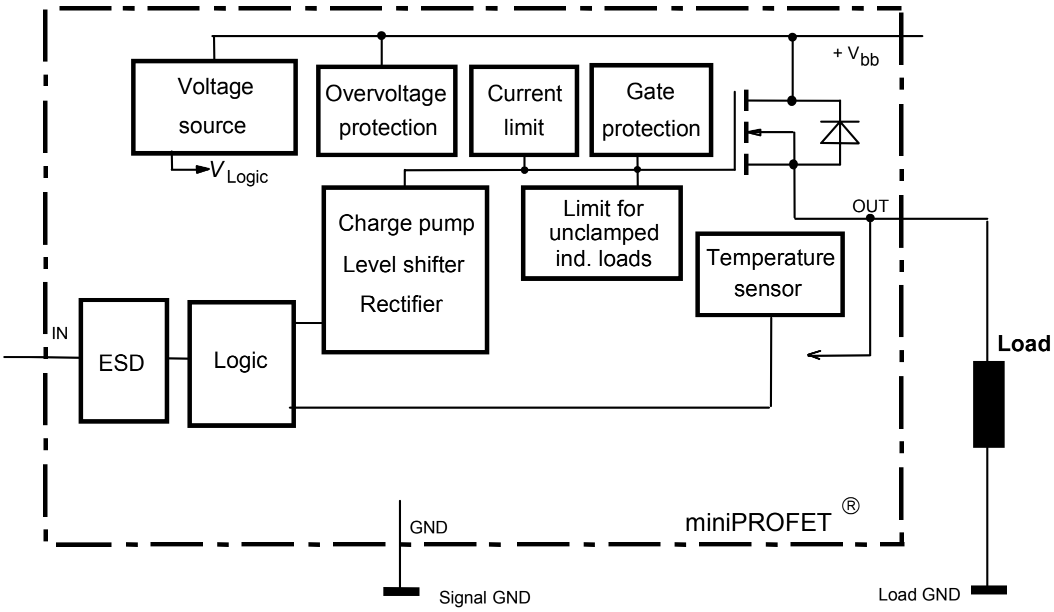
Application

- All types of resistive, inductive and capacitive loads
- µC compatible power switch for 12 V, 24 V and 42 V DC industrial applications
- Replaces electromechanical relays and discrete circuits

General Description

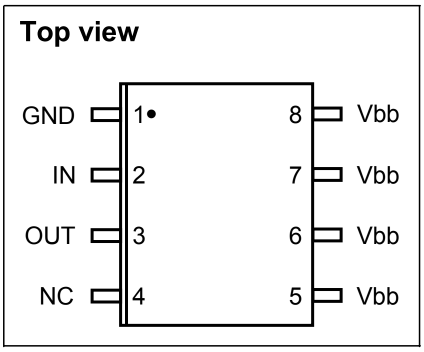
N channel vertical power FET with charge pump, ground referenced CMOS compatible input, monolithically integrated in Smart SIPMOS® technology.
Providing embedded protective functions.

Block Diagram



Pin	Symbol	Function
1	GND	Logic ground
2	IN	Input, activates the power switch in case of logic high signal
3	OUT	Output to the load
4	NC	not connected
5	Vbb	Positive power supply voltage
6	Vbb	Positive power supply voltage
7	Vbb	Positive power supply voltage
8	Vbb	Positive power supply voltage

Pin configuration



Maximum Ratings at T_j = 25 °C, unless otherwise specified

Parameter	**Symbol**	**Value**	**Unit**
Supply voltage	V_{bb}	52	V
Supply voltage for full short circuit protection	$V_{bb(SC)}$	50	
Continuous input voltage	V_{IN}	-10 ... +16	
Load current (Short - circuit current, see page 5)	I_L	self limited	A
Current through input pin (DC)	I_{IN}	± 5	mA
Junction temperature	T_j	150	°C
Operating temperature	T_a	-30...+85	
Storage temperature	T_{stg}	-40 ... +105	
Power dissipation [1]	P_{tot}	1.5	W
Inductive load switch-off energy dissipation[1)2)] single pulse, (see page 8) Tj =150 °C, I_L = 1 A	E_{AS}	125	mJ
Load dump protection[2)] $V_{LoadDump}$[3)]= V_A + V_S R_I=2Ω, t_d=400ms, V_{IN}= low or high, V_A=13,5V R_L = 13.5 Ω R_L = 27 Ω	$V_{Loaddump}$	 73.5 83.5	V
Electro**s**tatic **d**ischarge voltage (Human Body Model) according to ANSI EOS/ESD - S5.1 - 1993 ESD STM5.1 - 1998 Input pin all other pins	V_{ESD}	 ± 1 ± 5	kV

Thermal Characteristics

Thermal resistance @ min. footprint	$R_{th(JA)}$	-	95	-	K/W
Thermal resistance @ 6 cm^2 cooling area [1]	$R_{th(JA)}$	-	70	83	

[1]Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

[2]not subject to production test, specified by design

[3]$V_{Loaddump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839 .

Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND pin, e.g. with a 150Ω resistor in GND connection. A resistor for the protection of the input is integrated.

Electrical Characteristics

Parameter and Conditions at T_j = -40...+150°C, V_{bb} = 12..42V, unless otherwise specified	Symbol	Values min.	Values typ.	Values max.	Unit
Load Switching Capabilities and Characteristics					
On-state resistance T_j = 25 °C, I_L = 1 A, V_{bb} = 9...52 V T_j = 150 °C	R_{ON}	 - -	 150 270	 200 380	mΩ
Nominal load current; Device on PCB [1)] T_C = 85 °C, $T_j \leq$ 150 °C	$I_{L(nom)}$	1.3	1.7	-	A
Turn-on time to 90% V_{OUT} R_L = 47 Ω	t_{on}	-	80	180	µs
Turn-off time to 10% V_{OUT} R_L = 47 Ω	t_{off}	-	80	200	
Slew rate on 10 to 30% V_{OUT}, R_L = 47 Ω, V_{bb} = 13.5 V	dV/dt_{on}	-	0.7	2	V/µs
Slew rate off 70 to 40% V_{OUT}, R_L = 47 Ω, V_{bb} = 13.5 V	$-dV/dt_{off}$	-	0.9	2	

Operating Parameters

Operating voltage	$V_{bb(on)}$	6	-	52	V
Undervoltage shutdown of charge pump T_j = -40...+85 °C T_j = 150 °C	$V_{bb(under)}$	 - -	 - -	 4 5.5	
Undervoltage restart of charge pump	$V_{bb(u\ cp)}$	-	4	5.5	
Standby current T_j = -40...+85 °C, V_{IN} = low T_j = +150 °C[2)] , V_{IN} = low	$I_{bb(off)}$	 - -	 - -	 15 18	µA
Leakage output current (included in $I_{bb(off)}$) V_{IN} = low	$I_{L(off)}$	-	-	5	
Operating current V_{IN} = high	I_{GND}	-	0.8	2	mA

[1]Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

[2]higher current due temperature sensor

Electrical Characteristics

Parameter and Conditions	Symbol	Values			Unit
at T_j = -40...+150°C, V_{bb} = 12..42V, unless otherwise specified		min.	typ.	max.	
Protection Functions[1]					
Initial peak short circuit current limit (pin 5 to 3)	$I_{L(SCp)}$				A
T_j = -40 °C, V_{bb} = 20 V, t_m = 150 µs		-	-	9	
T_j = 25 °C		-	6.5	-	
T_j = 150 °C		4	-	-	
T_j = -40...+150 °C, V_{bb} > 40 V , (see page 11)		-	5[2]	-	
Repetitive short circuit current limit	$I_{L(SCr)}$				
$T_j = T_{jt}$ (see timing diagrams)					
V_{bb} < 40 V		-	6	-	
V_{bb} > 40 V		-	4.5	-	
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$, I_{bb} = 4 mA	$V_{ON(CL)}$	59	63	-	V
Overvoltage protection [3] I_{bb} = 4 mA	$V_{bb(AZ)}$	62	-	-	
Thermal overload trip temperature	T_{jt}	150	-	-	°C
Thermal hysteresis	ΔT_{jt}	-	10	-	K

Reverse Battery

Reverse battery[4]	$-V_{bb}$	-	-	52	V
Drain-source diode voltage ($V_{OUT} > V_{bb}$) T_j = 150 °C	$-V_{ON}$	-	600	-	mV

[1]Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

[2]not subject to production test, specified by design

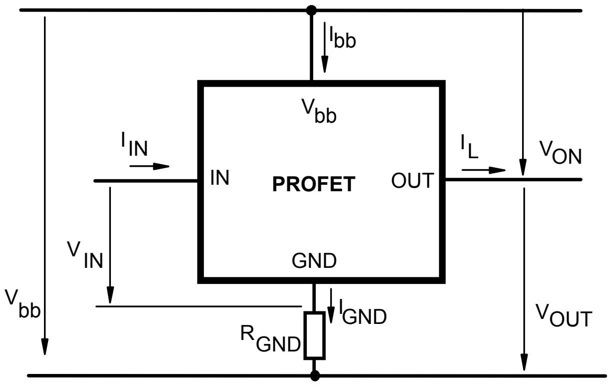
[3] see also $V_{ON(CL)}$ in circuit diagram on page 7

[4]Requires a 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Power dissipation is higher compared to normal operating conditions due to the voltage drop across the drain-source diode. The temperature protection is not active during reverse current operation! Input current has to be limited (see max. ratings page 3).

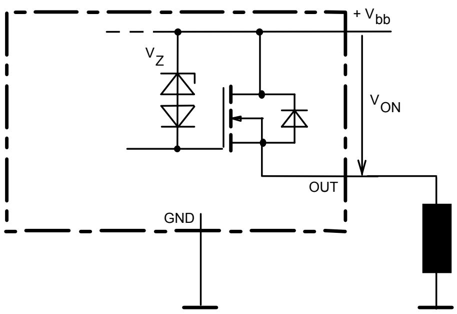
Electrical Characteristics

Parameter and Conditions at T_j = -40...+150°C, V_{bb} = 12..42V, unless otherwise specified	**Symbol**	**Values** min.	typ.	max.	**Unit**
Input					
Input turn-on threshold voltage	$V_{IN(T+)}$	-	-	2.2	V
Input turn-off threshold voltage	$V_{IN(T-)}$	0.8	-	-	
Input threshold hysteresis	$\Delta V_{IN(T)}$	-	0.4	-	
Off state input current V_{IN} = 0.7 V	$I_{IN(off)}$	1	-	25	µA
On state input current V_{IN} = 5 V	$I_{IN(on)}$	3	-	25	
Input resistance (see page 7)	R_I	2	3.5	5	kΩ

Terms

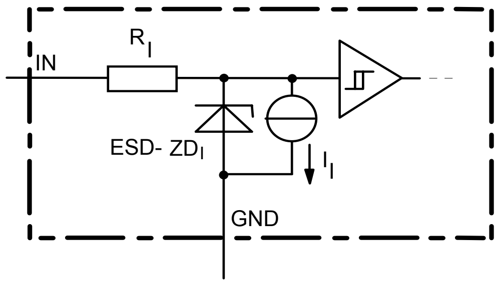


Inductive and overvoltage output clamp



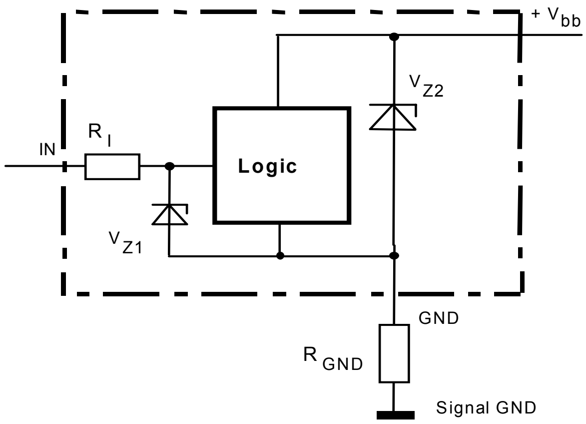
V_{ON} clamped to 59V min.

Input circuit (ESD protection)



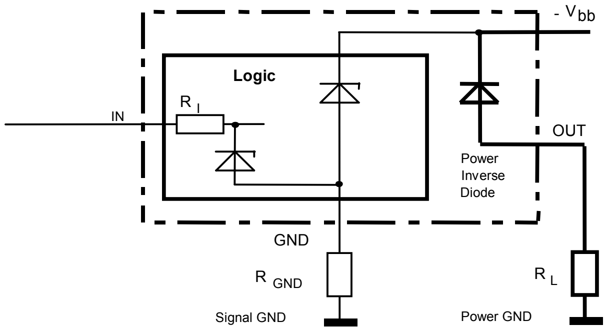
The use of ESD zener diodes as voltage clamp at DC conditions is not recommended

Overvoltage protection of logic part



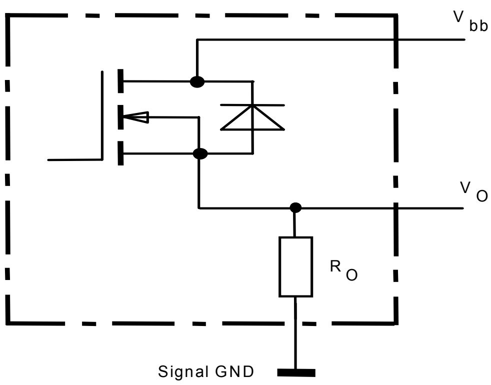
V_{Z1}=6.1V typ., V_{Z2}=$V_{bb(AZ)}$=62V min.,
R_I=3.5 kΩ typ., R_{GND}=150Ω

Reverse battery protection



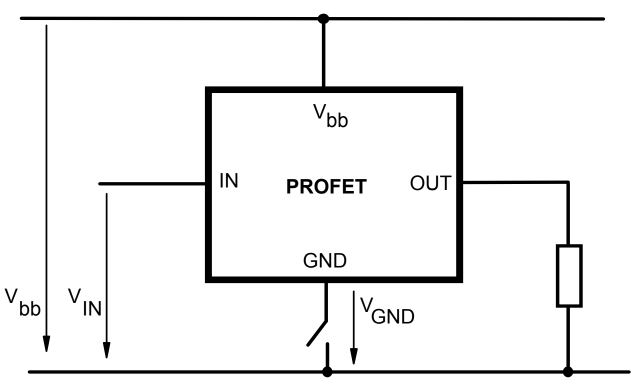
R_{GND}=150Ω, R_I=3.5kΩ typ.,
Temperature protection is not active during inverse current

Internal output pull down

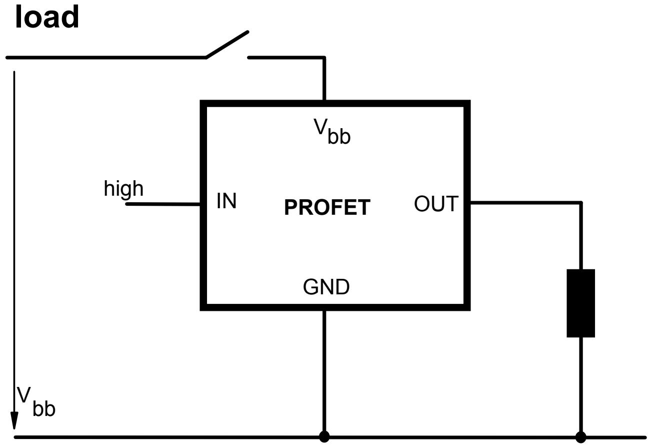


R_O = 200 kΩ typ.

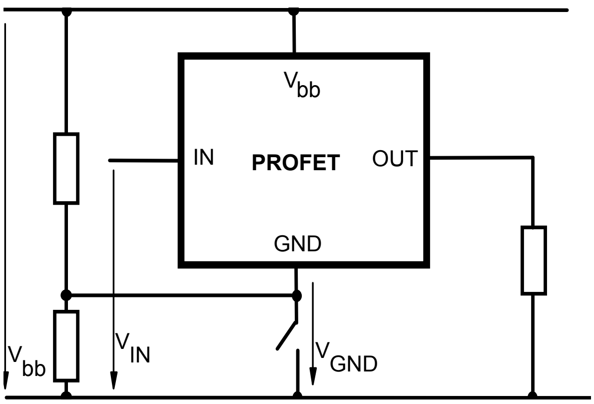
GND disconnect



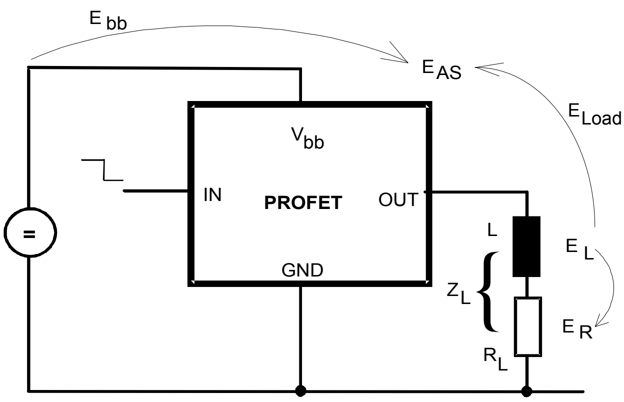
V_{bb} disconnect with charged inductive load



GND disconnect with GND pull up



Inductive Load switch-off energy dissipation



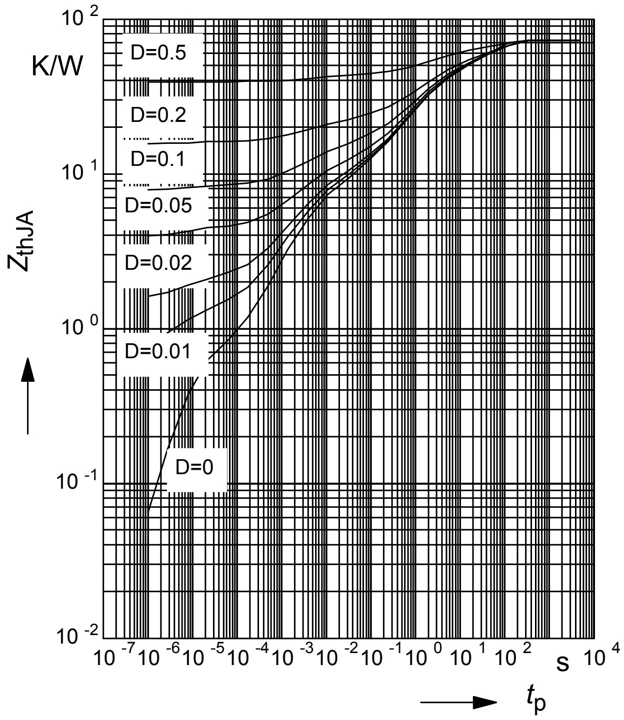
Energy stored in load inductance: $E_L = ½ * L * I_L^2$
While demagnetizing load inductance,
the enérgy dissipated in PROFET is
$E_{AS} = E_{bb} + E_L - E_R = V_{ON(CL)} * i_L(t)$ dt,
with an approximate solution for $R_L > 0\Omega$:

$$E_{AS} = \frac{I_L * L}{2 * R_L} * (V_{bb} + |V_{OUT(CL)}|) * \ln\left(1 + \frac{I_L * R_L}{|V_{OUT(CL)}|}\right)$$

Typ. transient thermal impedance

Z_{thJA}=f(t_p) @ 6cm^2 heatsink area

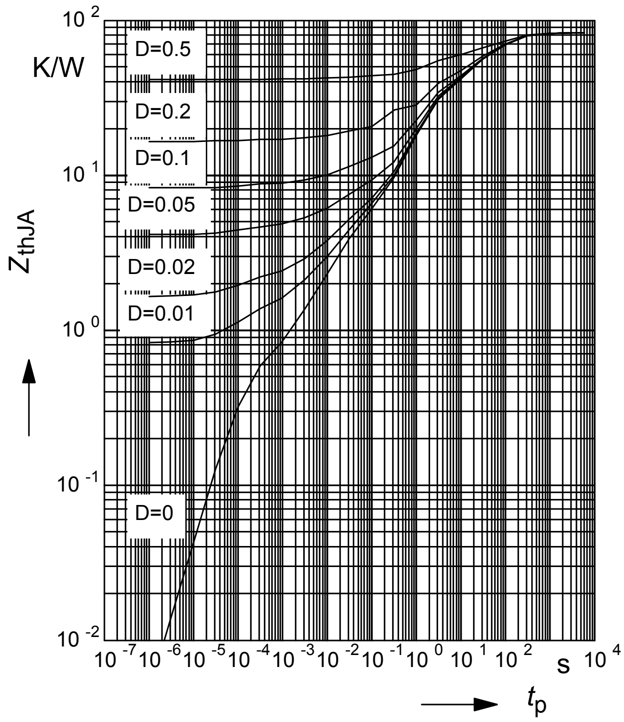
Parameter: $D=t_p/T$



Typ. transient thermal impedance

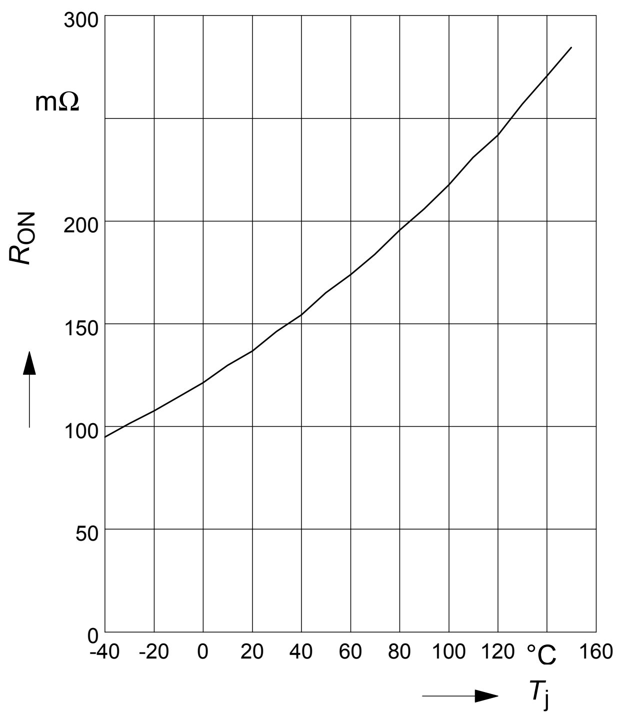
Z_{thJC}=f(t_p) @ min. footprint

Parameter: $D=t_p/T$



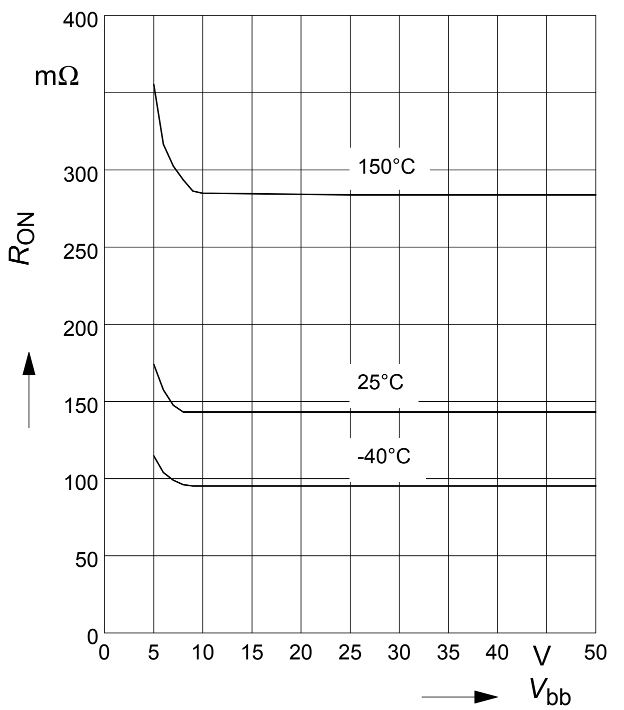
Typ. on-state resistance

R_{ON} = f(T_j) ; V_{bb} = 13,5V ; V_{in} = high



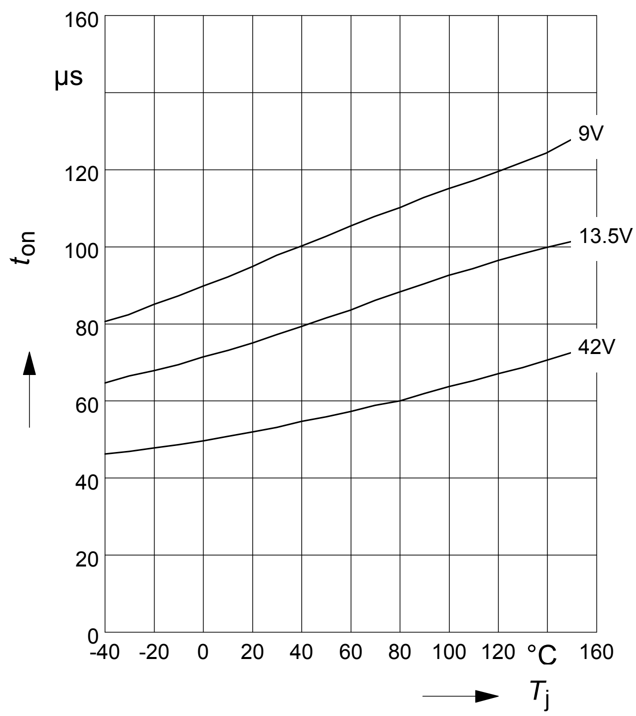
Typ. on-state resistance

R_{ON} = f(V_{bb}); I_L = 1 A ; V_{in} = high



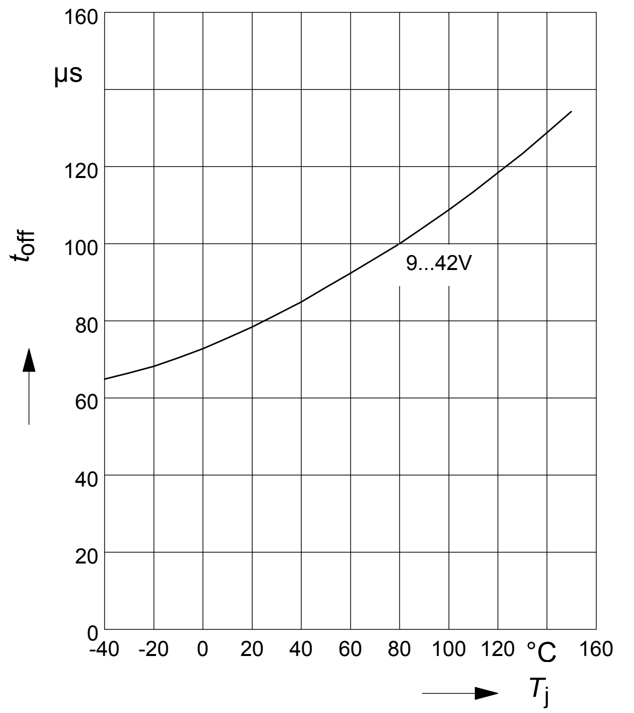
Typ. turn on time

$t_{on} = f(T_j)$; $R_L = 47\Omega$



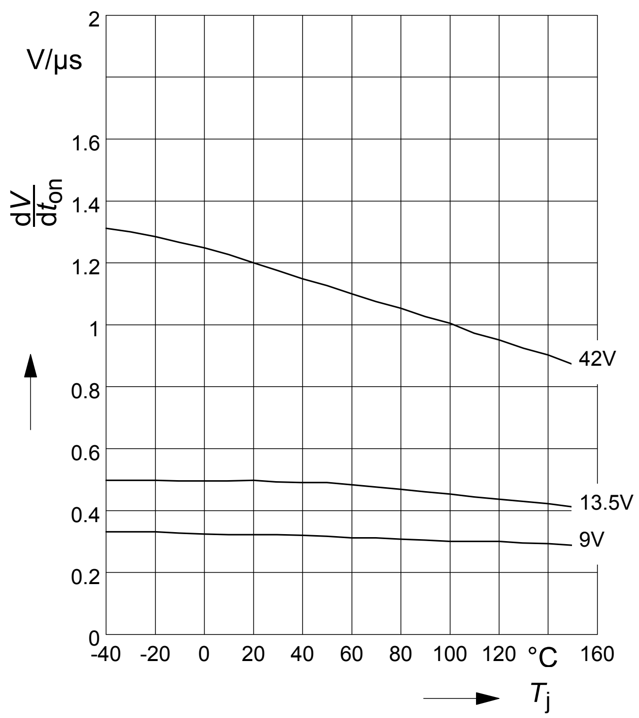
Typ. turn off time

$t_{off} = f(T_j)$; $R_L = 47\Omega$



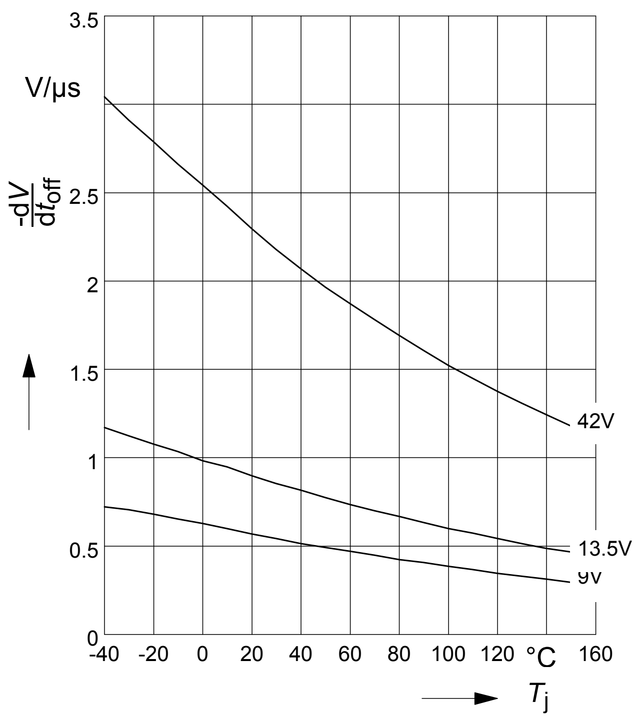
Typ. slew rate on

$dV/dt_{on} = f(T_j)$; $R_L = 47\ \Omega$



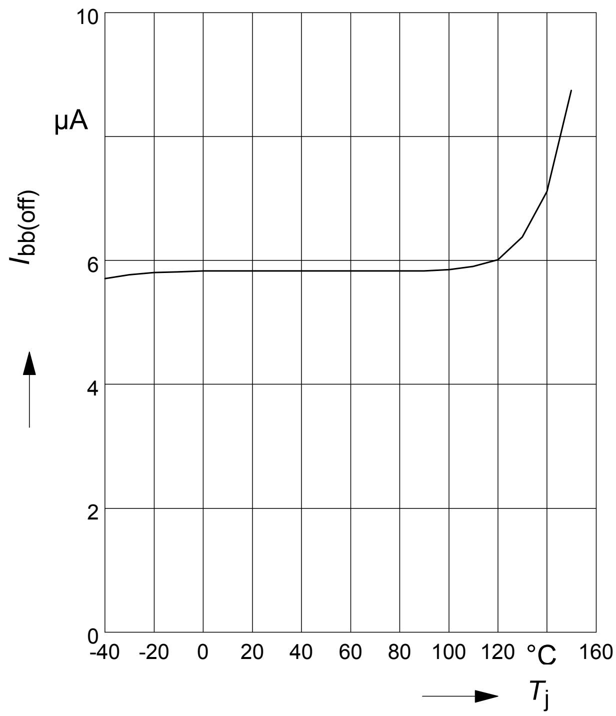
Typ. slew rate off

$dV/dt_{off} = f(T_j)$; $R_L = 47\ \Omega$



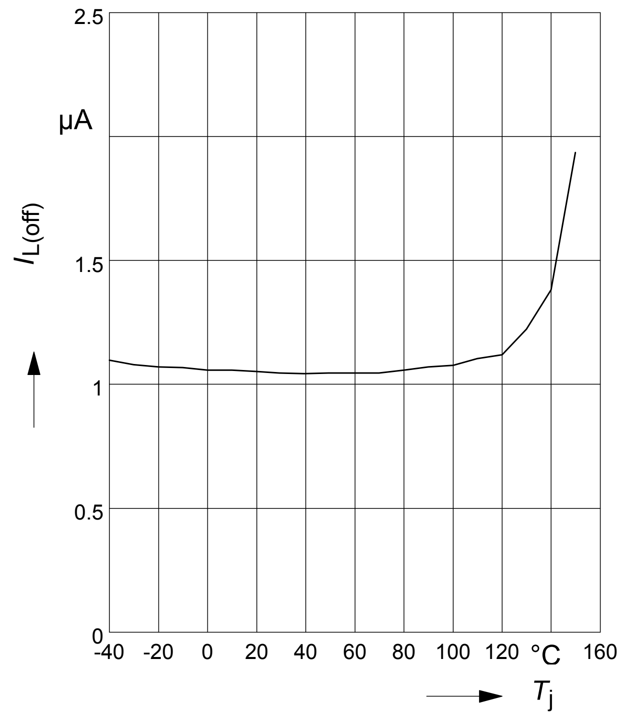
Typ. standby current

$I_{bb(off)} = f(T_j)$; V_{bb} = 42V ; V_{IN} = low



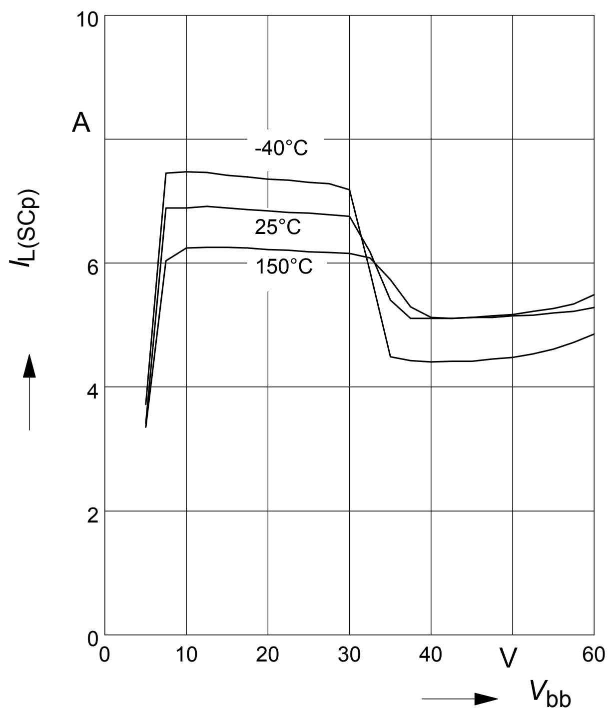
Typ. leakage current

$I_{L(off)} = f(T_j)$; V_{bb} = 42V ; V_{IN} = low



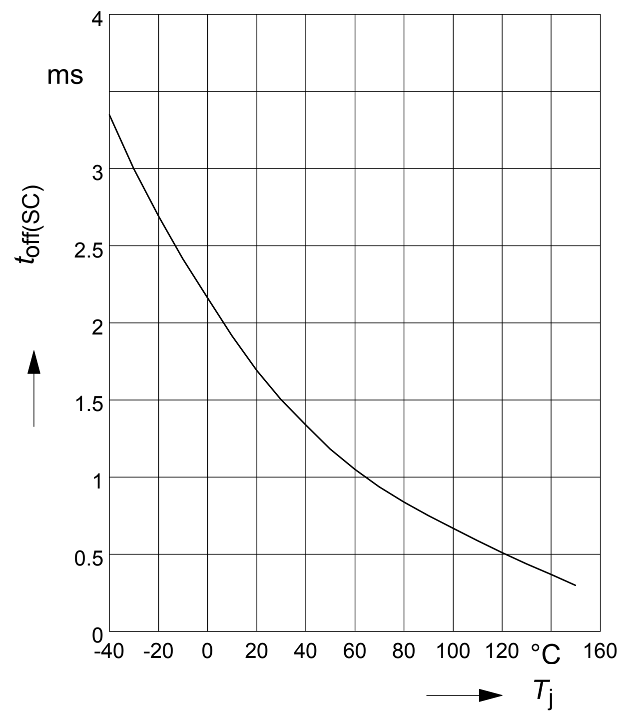
Typ. initial peak short circuit current limit

$I_{L(SCp)} = f(V_{bb})$



Typ. initial short circuit shutdown time

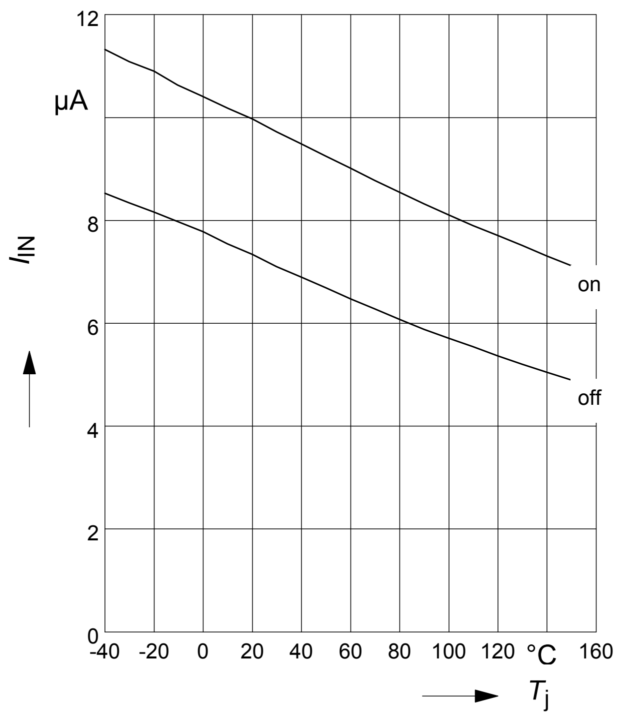
$t_{off(SC)} = f(T_{j,start})$; V_{bb} = 20V



Typ. input current

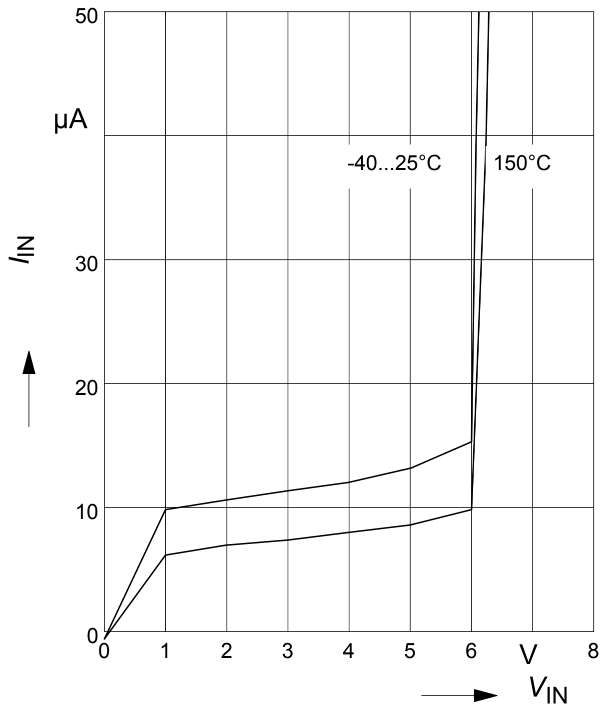
$I_{IN(on/off)} = f(T_j)$; V_{bb} = 13,5V; V_{IN} = low/high

$V_{INlow} \leq 0{,}7V$; V_{INhigh} = 5V



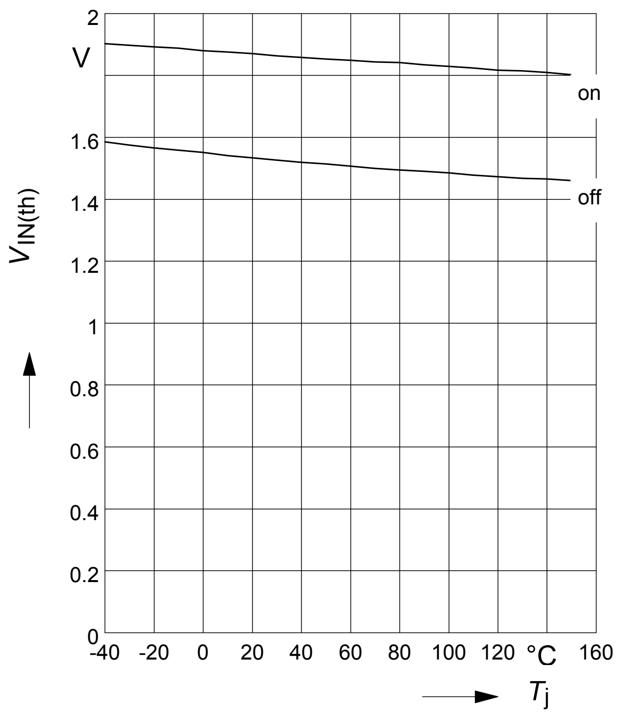
Typ. input current

$I_{IN} = f(V_{IN})$; V_{bb} = 13.5V



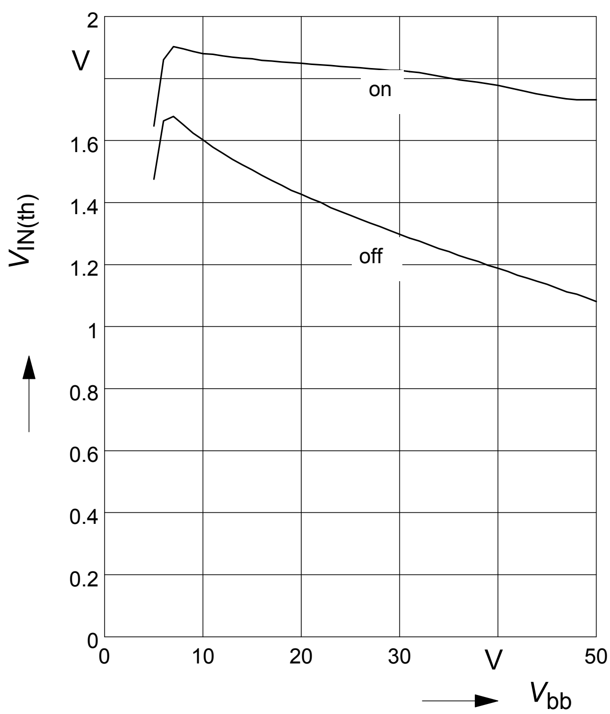
Typ. input threshold voltage

$V_{IN(th)} = f(T_j)$; V_{bb} = 13,5V



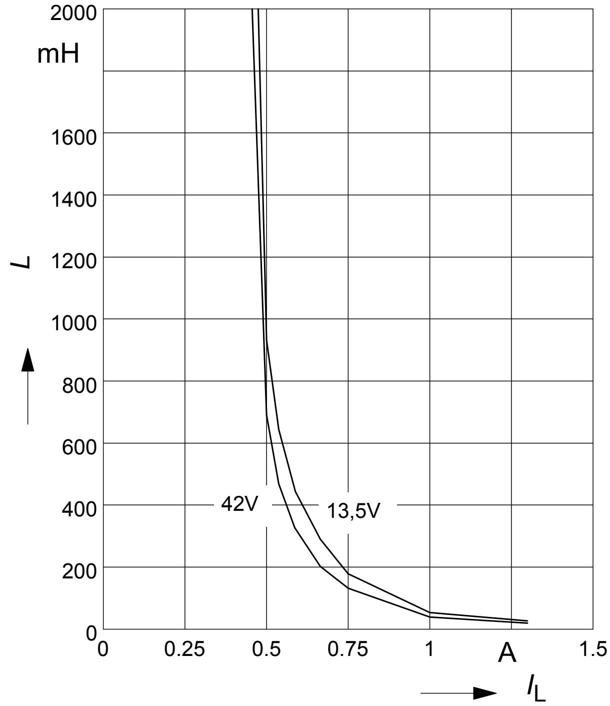
Typ. input threshold voltage

$V_{IN(th)} = f(V_{bb})$; T_j = 25°C



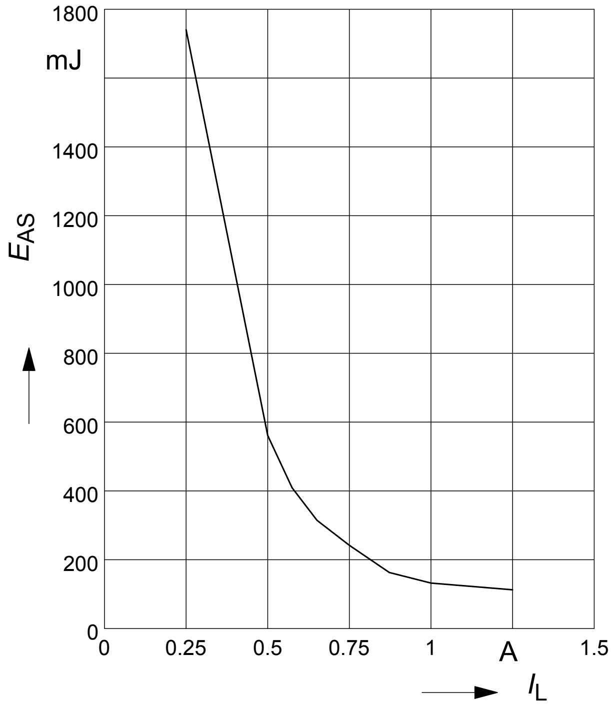
Maximum allowable load inductance for a single switch off

***L* = f(*I*$_L$)**; T_{jstart}=150°C, R_L=0Ω



Maximum allowable inductive switch-off energy, single pulse

***E*$_{AS}$ = f(*I*$_L$)**; T_{jstart} = 150°C, V_{bb} = 13,5V



Timing diagrams

Figure 1a: Vbb turn on:

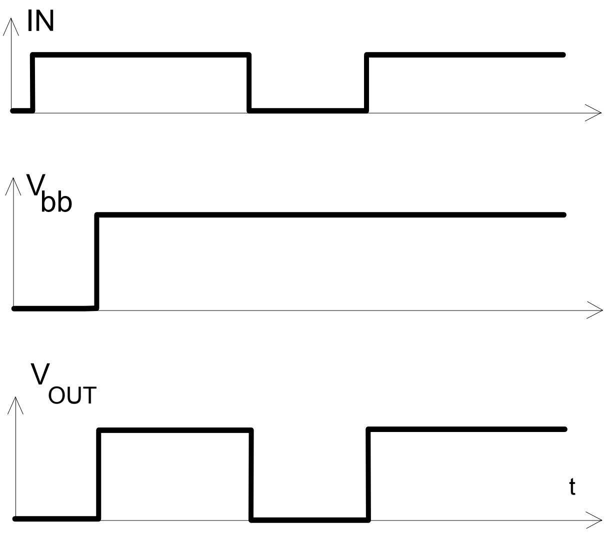


Figure 2b: Switching a lamp,

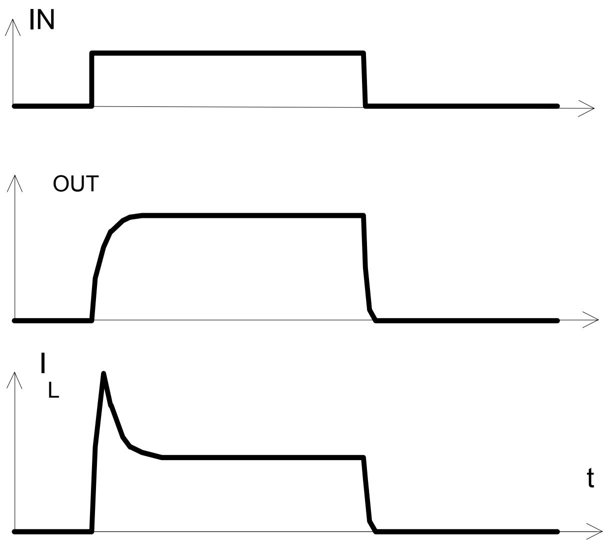


Figure 2a: Switching a resistive load, turn-on/off time and slew rate definition

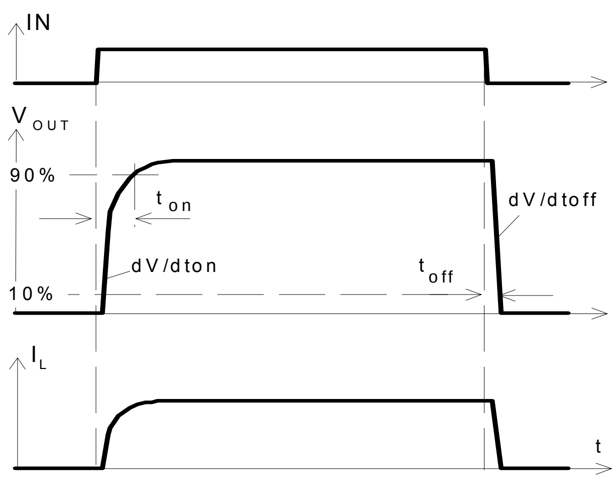


Figure 2c: Switching an inductive load

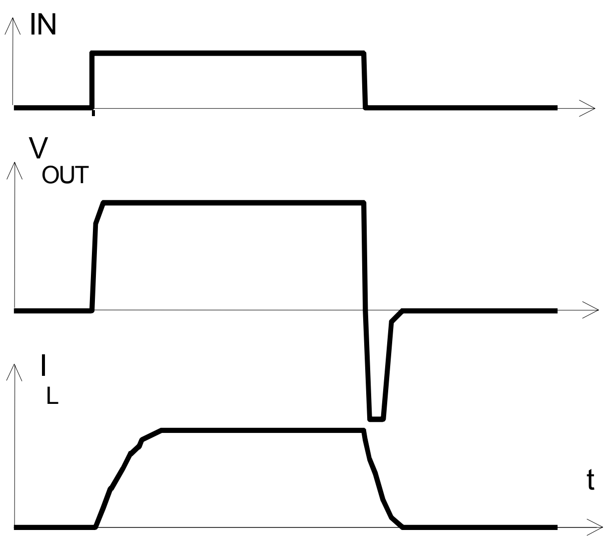
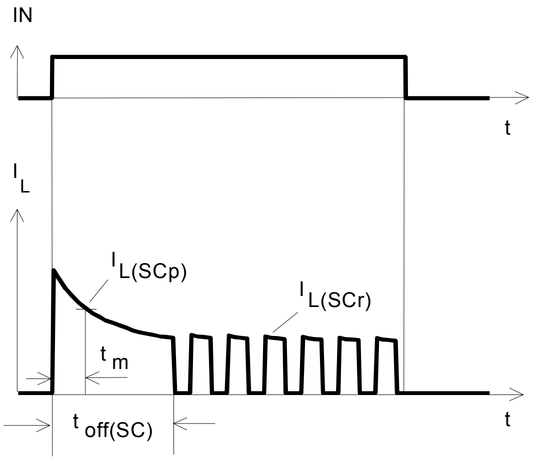


Figure 3a: Turn on into short circuit,
shut down by overtemperature, restart by cooling



Heating up of the chip may require several milliseconds, depending on external conditions.

Figure 4: Overtemperature:
Reset if $T_j < T_{jt}$

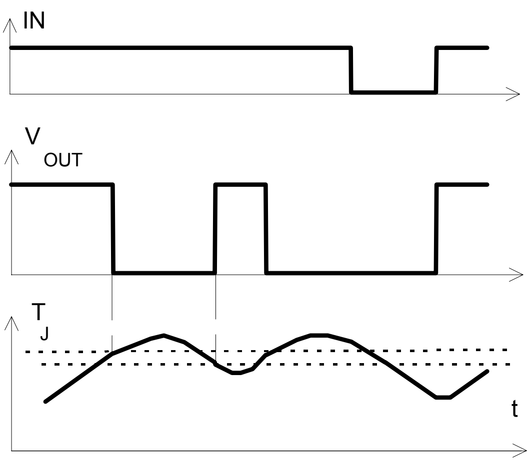
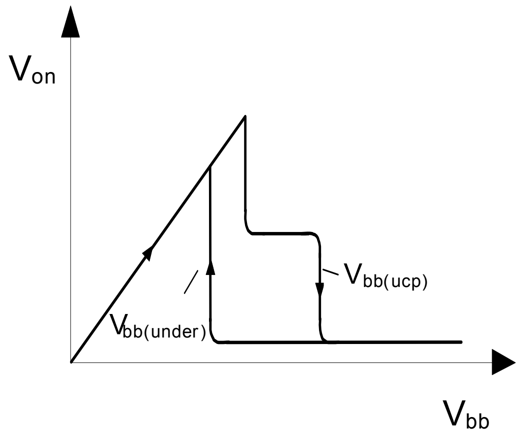


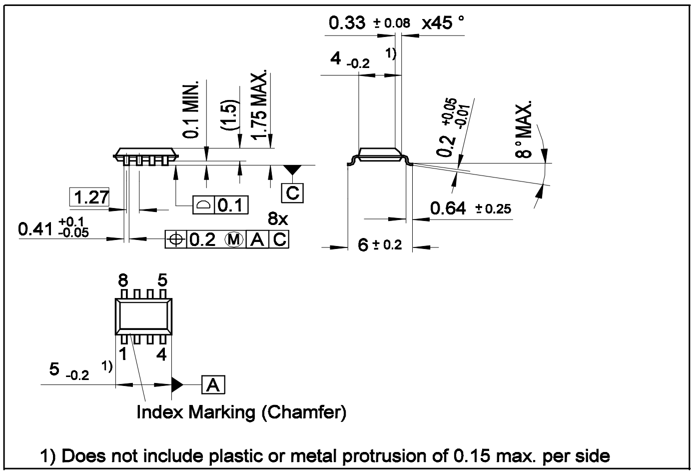
Figure 5: Undervoltage restart of charge pump

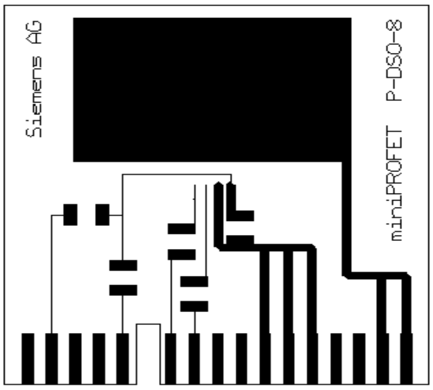


Package and ordering code

all dimensions in mm

Package:	Ordering code:
PG-DSO-8	SP000211730





Printed circuit board (FR4, 1.5mm thick, one layer 70µm, 6cm^2 active heatsink area) as a reference for max. power dissipation P_{tot} nominal load current $I_{L(nom)}$ and thermal resistance R_{thja}

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